Product End-of-Life Disassembly Instructions

Product Category: Servers
Marketing Name / Model [List multiple models if applicable.]
HP Proliant ML150G3 / ML150G3 DP3.0/667 2X2M 5050 NHP SATA HP Proliant ML150G3 / ML150G3 DP3.0/667 2X2M 5050 HP SATA
HP Proliant ML150G3 / ML150G3 DP3.0/667 2X2M 5050 HP SAS HP Proliant ML150G3 / ML150G3 WS1.60/1066 5110 HP SATA
HP Proliant ML150G3 / ML150G3 WS1.60/1066 5110 NHP SATA
HP Proliant ML150G3 / ML150G3 WS1.86/1066 5120 HP SATA HP Proliant ML150G3 / ML150G3 WS2.00/1333 5130 HP SATA
HP Proliant ML150G3 / ML150G3 WS2.00/1333 5130 HP SAS HP Proliant ML150G3 / ML150G3 CT1.6/1066 HP SAS

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	3
Batteries	All types including standard alkaline and lithium coin or button style batteries	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	
Cathode Ray Tubes (CRT)		
Capacitors / condensers (Containing PCB/PCT)		
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		15
External electrical cables and cords		
Gas Discharge Lamps		
Plastics containing Brominated Flame Retardants		
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	
Components and waste containing asbestos		

Components, parts and materials containing refractory ceramic fibers		
Components, parts and materials containing radioactive substances		

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Torx Driver	T-15
Philips Driver	# 2
Flat Head Screw Driver	Medium

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

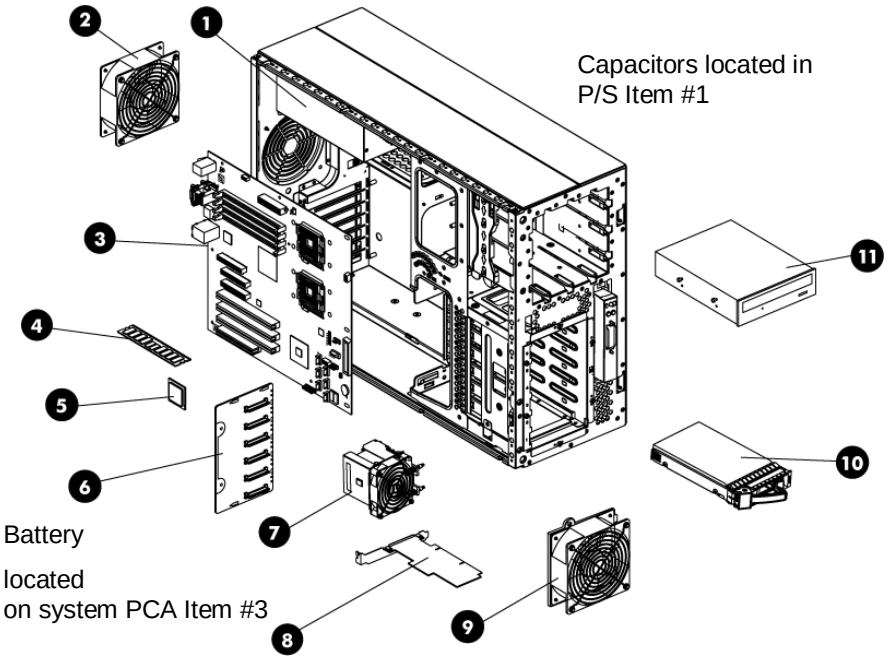
1. System Board Battery - Remove the top cover and locate the battery on the system board. With a medium flat head screw driver remove the battery and dispose of properly.
2. Capacitors>2.5CM - Remove thepower supply(s) from the system. With #2 Philips screw driver, remove the screws securing the top cover and the heatsinks in the P/S, then locate the capacitors and pry from the PCB with a medium flat head screw driver and dispose of properly.
3.
4.
5.
6.
7.
8.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

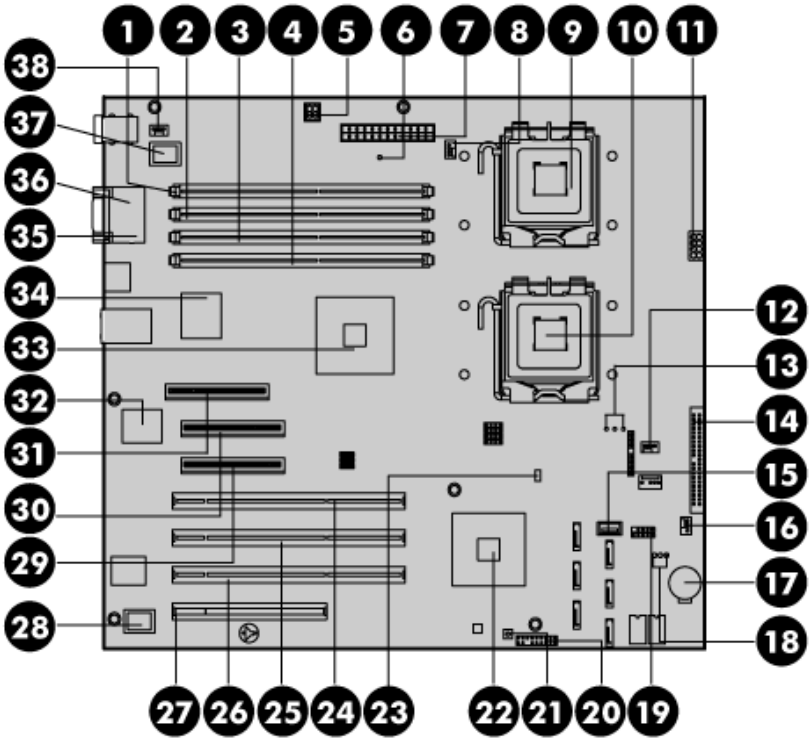
Attachment 1 – Disassembly Diagram

Attachment 2 –System Battery Location

Attachment 3 – Capacitors Location

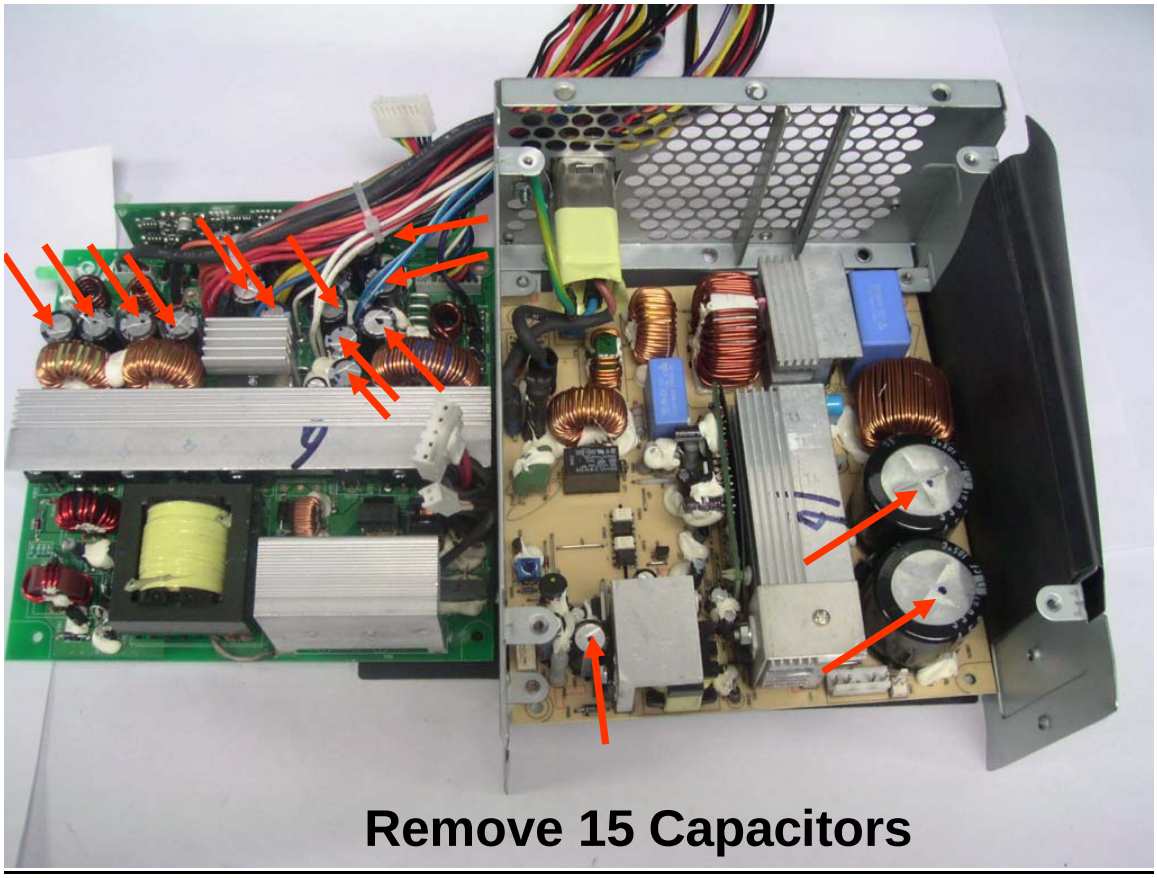


Attachment 1



Remove system battery Item #17

Attachment 2



Attachment 3